



## **TSS0230U**

# 0.2Amp Surface Mount Schottky Barrier Diode

### 0603



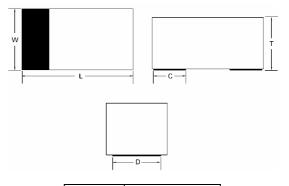


#### **Features**

- ♦ Designed for mounting on small surface
- Extremely thin/leadless package
- ♦ Low capacitance
- ♦ Low forward voltage drop
- High temperature soldering:
   260°C/10 seconds at terminals
- ♦ Chip version in 0603

#### **Mechanical Data**

- ♦ Case: 0603 Standard package, molded plastic
- Terminals: Gold plated, solderable per MIL-STD-750, method 2026.
- ♦ Polarity: Indicated by cathode band
- ♦ Mounting position: Any
- ♦ Package code: BB
- ♦ Weight: 0.003 gram (approximately)



ITEM	0603		
L	0.071(1.80)		
	0.063(1.60)		
W	0.039(1.00)		
	0.031(0.80)		
Т	0.033(0.85)		
	0.027(0.70)		
С	0.018(0.45)		
	Typical		
D	0.028(0.70)		
	Typical		

#### Dimensions in inches and (millimeters)

## **Maximum Ratings and Electrical characteristics**

Rating at 25 °C ambient temperature unless otherwise specified. Single phase, half wave, 60 Hz, resistive or inductive load. For capacitive load, derate current by 20%

Type Number	Symbol	0603	Units
Repetitive Peak Reverse Voltage	$V_{RRM}$	35	V
DC Reverse Voltage	$V_R$	30	V
Average Forward Current	Io	200	mA
Peak Forward Surge Current 8.3ms single half sine-wave superimposed on rate load (JEDEC method)	I <sub>FSM</sub>	1.0	А
Power Dissipation	Pd	150	mW
Forward Voltage @ IF=200mA	V <sub>F</sub>	0.6	V
Reverse Leakage Current  VR=1 0V	I <sub>R</sub>	1.0	uA
Typical capacitance between terminals VR=1V, f =1.0MHz reverse voltage	С	1.5	pF
Junction Temperature	Τ <sub>J</sub>	-40 to + 125	°C
Storage Temperature	T <sub>STG</sub>	-40 to + 125	°C